

Abstract of the Disclosure

In a semiconductor element test apparatus and a method of testing a semiconductor element using the apparatus, a plurality of probe needles are brought into contact with semiconductor elements fabricated on a 5 semiconductor wafer, and a structure is provided for attaching a probe card and a reinforcement member to a probe card hold member. In a plurality of mount positions in which a probe card substrate and a reinforcement member are attached to a probe card hold member, counterbores are formed so as to assume substantially the same depth 10 and shape. Analogous mount structures are realized at a plurality of mount positions by way of the counterbores.

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